



SOT765-1

plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

5 July 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	VSSOP8
Package type industry code	VSSOP8
Package style descriptive code	VSSOP (very thin shrink small outline package)
Package body material type	P (plastic)
JEDEC package outline code	MO-187
Mounting method type	S (surface mount)
Issue date	31-5-2016

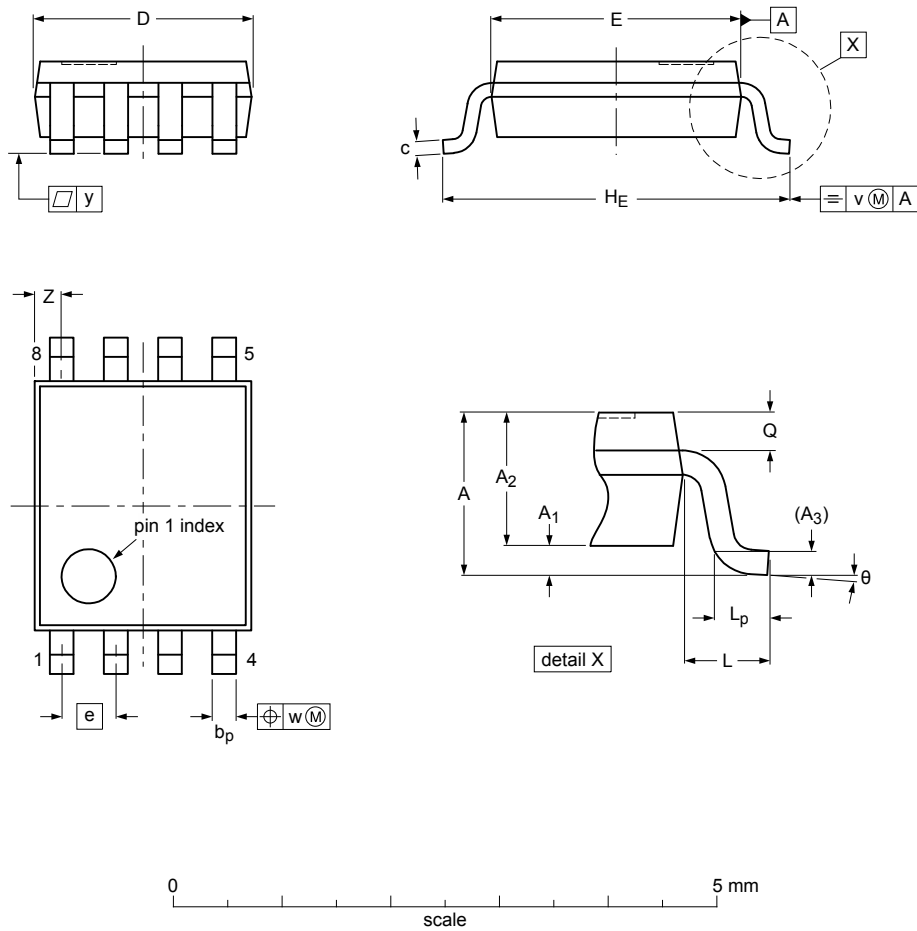
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	2.2	-	2.3	2.4	mm
A	seated height	-	-	1	1	mm
A ₂	package height	0.6	-	0.75	0.85	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	8	-	



2. Package outline

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm SOT765-1



Dimensions (mm are the original dimensions)

Unit	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
max		0.15	0.85		0.27	0.23	2.1	2.4		3.2	0.4	0.40	0.21				0.4	8°
nom	1			0.12					0.5		0.4			0.2	0.08	0.1		
min		0.00	0.60		0.17	0.08	1.9	2.2		3.0	0.15	0.19					0.1	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

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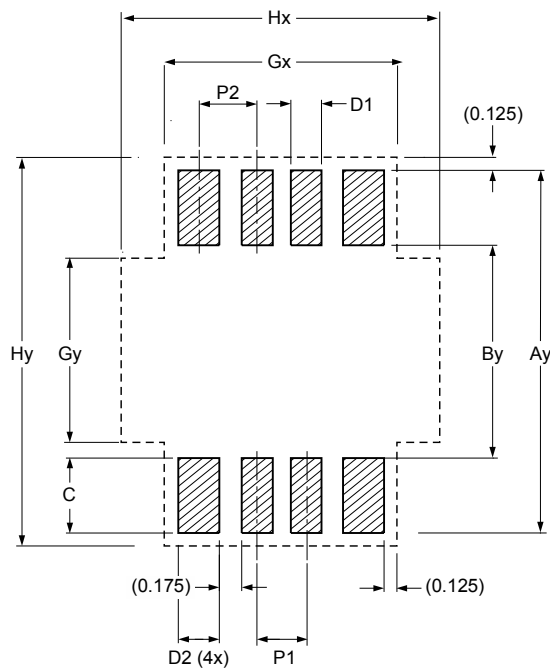
Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT765-1		MO-187			-07-06-02-16-05-31

Fig. 1. Package outline VSSOP8 (SOT765-1)


3. Soldering

Footprint information for reflow soldering of VSSOP8 package

SOT765-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
- - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.550	3.500	2.000	0.750	0.300	0.400	2.250	1.750	3.075	3.750

sot765-1_fr

Fig. 2. Reflow soldering footprint for VSSOP8 (SOT765-1)

4. Legal information

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